What is claimed is:

1. A heat sink assembly with integrated electronics comprising:

a cover having at least one side open for exposing an interior cavity, said cover being made of a material having the capability of withstanding high temperatures;

at least one hybrid circuit housed in said cavity and having interconnect capability available at said open side of said cover;

a bottom for attachment to and sealing of said at least one open side of said cover, said bottom being made from a material having heat sink capabilities and having a plurality of interconnect pins molded therein, said pins providing electrical interconnect capabilities between said at least one hybrid circuit and an external device.

2. The heat sink assembly as claimed in claim 1 wherein said cover further comprises a track molded in an edge of said open side, and wherein said bottom has a bead molded therein for interconnection with said track in said open side of said cover.

3. The heat sink assembly as claimed in claim 2 wherein an adhesive is applied to said track thereby sealing said bottom to said cover.

4. The heat sink assembly as claimed in claim 1 wherein said bottom is cast aluminum.

5. The heat sink assembly as claimed in claim 1 wherein said pins are wire bond compatible at one end for connection to said at least one hybrid circuit and said pins are solderable at another end for connection to said external device.

6. The heat sink assembly as claimed in claim 1 wherein said sealed cover and bottom are filled with a dielectric gel material.

7. The heat sink assembly as claimed in claim 1 wherein said cover has partitions separating said at least one hybrid circuit from another hybrid circuit housed in said cover.

8. A housing for a plurality of electronic components comprising:

a heat sink section having at least one opening therein defining a cavity for housing said plurality of electronic components;

a bottom section having pins for electrical connection of said plurality of electronic components and an external device;

means for attaching said bottom section to said heat sink section thereby fully enclosing and sealing said electronic components in said housing.

9. The housing as claimed in claim 8 further comprising a dielectric gel enclosed in said sealed housing.

10. The housing as claimed in claim 8 wherein said means for attaching said bottom section to said heat sink section further comprises a tongue and groove attachment between said bottom section and said heat sink section.

11. The housing as claimed in claim 10 wherein said tongue and groove attachment further comprises an adhesive for sealing said attachment.

12. The housing as claimed in claim 8 wherein said pins are wire bond compatible at one end for connection to said plurality of electronic components and said pins are solderable at another end for connection to said external device.

13. The housing as claimed in claim 1 wherein said heat sink cavity has partitions for separating said electronic components.

14. A heat sink with integrated electronics comprising:

a cast aluminum housing having a cavity therein for housing said integrated electronics, said cast aluminum housing having an open side;

a high temperature plastic bottom portion for covering said open side of said cast aluminum housing and sealing said integrated electronics therein, said bottom portion having pins molded therein for making electrical connections between said integrated electronics and an external device.

15. The heat sink as claimed in claim 14 wherein said sealed housing has a dielectric gel therein.

16. The heat sink as claimed in claim 13 wherein said housing and said bottom portion are attached to each other by a tongue and groove connection.

17. The heat sink as claimed in claim 16 wherein said tongue and groove connection is sealed by an adhesive material.

18. The heat sink as claimed in claim 13 wherein said bottom portion further comprises means for mechanical connection to said external device.

19. The heat sink as claimed in claim 13 wherein said pins are wire bond compatible with said integrated electronics housed inside said cavity and solderable to said external device.